IN THE CLAIMS

13 (canceled). ~~A method of manufacturing an electronic component to be mounted on a circuit board, said electronic component comprising:~~

~~a first substrate having an electronic circuit device and an electrode pad on one main surface of said first substrate in electrical connection with said electronic circuit device;~~

~~a sealing wall whose one face is closely adhered to said one main surface of said first substrate, said sealing wall being configured, to enclose said electronic circuit device with said electrode pad arranged outside of said sealing wall;~~

~~a second substrate closely adhered to the other face of said sealing wall;~~

~~an opening formed in said second substrate at a site confronting said electrode pad; and~~

~~an electrically conductive member extending through the interior of said opening for allowing said electrode pad and said circuit substrate to be electrically connectable to each other;~~

~~said method comprising:~~

~~a first step in which one faces of a plurality of sealing walls are closely adhered to one main surface of said first substrate which has a plurality of electronic circuit devices formed on said one main surface in a plurality of circuit regions and a plurality of electrode pads in electric connection with said plurality of electronic circuit devices, said plurality of sealing walls each configured to enclose each of said plurality of electronic circuit devices with each of said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and in which said second substrate is closely adhered to the other faces of said plurality of sealing~~

~~walls, said second substrate having a plurality of openings at sites confronting said plurality of electrode pads ;~~

~~a second step in which an electrically conductive member is formed on each of said plurality of electrode pads, said electrically conductive member, being electrically connected with each of said plurality of electrode pads; and~~

~~a third step in which said first substrate, together with said second substrate, is severed for each of said plurality of circuit regions, to obtain a plurality of electronic components~~.

14 (Previously Amended). A method of manufacturing an electronic component to be mounted on a circuit board, said electronic component comprising:

a first substrate having an electronic circuit device and an electrode pad on one main surface of said first substrate in electrical connection with said electronic circuit device;

a sealing wall whose one face is closely adhered to said one main surface of said first substrate, said sealing wall being configured, to enclose said electronic circuit device with said electrode pad arranged outside of said sealing wall;

a second substrate closely adhered to the other face of said sealing wall;

an opening formed in said second substrate at a site confronting said electrode pad; and

an electrically conductive member extending through the interior of said opening for allowing said electrode pad and said circuit substrate to be electrically connectable to each other;

said method comprising:

a first step in which one faces of a plurality of sealing walls are closely adhered to one main surface of said first substrate which has a plurality of electronic circuit devices formed on said one main surface in a plurality of circuit regions and a plurality of electrode pads in electric connection with said plurality of electronic circuit devices, said plurality of sealing walls each configured to enclose each of said plurality of electronic circuit devices with each of said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and in which said second substrate is closely adhered to the other faces of said plurality of sealing walls, said second substrate having a plurality of openings at sites confronting said plurality of electrode pads said plurality of sealing walls are closely adhered to said first substrate after formation of said plurality of sealing walls onto said second substrate,

a second step in which an electrically conductive member is formed on each of said plurality of electrode pads, said electrically conductive member, being electrically connected with each of said plurality of electrode pads; and

a third step in which said first substrate, together with said second substrate, is severed for each of said plurality of circuit regions, to obtain a plurality of electronic components.

15. (Currently Amended) A method of manufacturing an electronic component according to claim [~~13~~] 18, wherein said first step includes a step in which said plurality of sealing walls are closely adhered to said second substrate after formation of said plurality of sealing walls onto said first substrate.

16 (Currently Amended). A method of manufacturing an electronic component according to claim [~~13~~] 14, wherein

said second step includes a step in which said electrically conductive member is formed on each of said plurality of electrode pads through a corresponding one of said plurality of openings.

17. (Currently Amended) A method of manufacturing an electronic component according to claim [~~13~~] 14, wherein

said electrically conductive member comprises a bump.

18. (Previously Amended) A method of manufacturing an electronic component to be mounted on a circuit board, said electronic component comprising:

a first substrate having an electronic circuit device and an electrode pad on one main surface of said first substrate in electrical connection with said electronic circuit device;

a sealing wall whose one face is closely adhered to said one main surface of said first substrate, said sealing wall being configured, to enclose said electronic circuit device with said electrode pad arranged outside of said sealing wall;

a second substrate closely adhered to the other face of said sealing wall;

an opening formed in said second substrate at a site confronting said electrode pad; and

an electrically conductive member extending through the interior of said opening for allowing said electrode pad and said circuit substrate to be electrically connectable to each other, said electrically conductive member comprises: a first bump disposed on each of said

plurality of electrode pads for electrical connection with said each of said plurality of electrode pads; and a second bump disposed on top of said first bump for electrical and physical connection with said circuit board;

said method comprising:

a first step in which one faces of a plurality of sealing walls are closely adhered to one main surface of said first substrate which has a plurality of electronic circuit devices formed on said one main surface in a plurality of circuit regions and a plurality of electrode pads in electric connection with said plurality of electronic circuit devices, said plurality of sealing walls each configured to enclose each of said plurality of electronic circuit devices with each of said plurality of electrode pads arranged outside of each of said plurality of sealing walls, and in which said second substrate is closely adhered to the other faces of said plurality of sealing walls, said second substrate having a plurality of openings at sites confronting said plurality of electrode pads said plurality of sealing walls are closely adhered to said first substrate after formation of said plurality of sealing walls onto said second substrate,

a second step in which an electrically conductive member by forming said first bump on each of said plurality of electrode pads through a corresponding one of said plurality of openings, after which said second bump is formed on top of said first bump, said electrically conductive member, being electrically connected with each of said plurality of electrode pads; and;

third step in which said first substrate, together with said second substrate, is severed for each of said plurality of circuit regions, to obtain a plurality of electronic components.

19. (Currently Amended) A method of manufacturing an electronic component according to claim [~~13~~] 14, wherein

a first electrically conductive member is formed on an inner wall of each of said plurality of openings, said first electrically conductive member being electrically connectable to said circuit board, and wherein

said second step includes a step in which, a second electrically conductive member is formed on each of said plurality of electrode pads, said second electrically conductive member electrically connecting said first electrically conductive member and each of said plurality of electrode pads.

20. (Currently Amended) A method of manufacturing an electronic component according to claim [~~13~~] 14, wherein

said second step is carried out after said first step.